

## IN THE CLAIMS

1. (currently amended) A carrier for used in manufacturing a semiconductor encapsulant package provided with a substrate having a side surface, which comprises:

at least one receiving part for used in receiving the semiconductor encapsulant package; and

a plurality of positioning pins protruding upwards from an edge of the receiving part for used in positioning the semiconductor encapsulant package on the carrier; wherein an obtuse angle  $\theta$  is between the positioning pin and the receiving part, and wherein a first plane of the positioning pin facing the semiconductor encapsulant package is slant, so that the first plane of the positioning pin is only abutted against a lower edge of the side surface of the substrate.

2. (original) The carrier as claimed in Claim 1, wherein the semiconductor encapsulant package exerts a friction force and a gliding force when contacting with the positioning pins, and the obtuse angle  $\theta$  between the positioning pin and the receiving part allows the friction force larger than the gliding force.

3. (original) The carrier as claimed in Claim 1, wherein the obtuse angle  $\theta$  between the positioning pin and receiving part is larger than  $91^\circ$ .

4. (previously presented) The carrier as claimed in Claim 1, wherein the obtuse angle  $\theta$  between the positioning pin and the receiving part is from  $91^\circ$  to  $110^\circ$ .

5. (previously presented) The carrier as claimed in Claim 1, wherein the obtuse angle  $\theta$  between the positioning pin and the receiving part is from  $91^\circ$  to  $96^\circ$ .
6. (currently amended) The carrier as claimed in Claim 1, wherein ~~a first plane of the positioning pin facing the semiconductor encapsulant package is slant and~~ a second plane of the positioning pin opposite the semiconductor encapsulant package is vertical, and ~~wherein the second plane of the positioning pin is at an angle of about  $90^\circ$  to the receiving part.~~
7. (original) The carrier as claimed in Claim 1, wherein a first plane of the positioning pins facing the semiconductor encapsulant package is slant and a second plane of the positioning pin opposite the semiconductor encapsulant package is also slant; wherein the second plane is substantially parallel to the first plane.
8. (original) The carrier as claimed in Claim 1, wherein the positioning pins and the receiving parts are integrally formed.
9. (previously presented) The carrier as claimed in Claim 2, wherein the obtuse angle  $\theta$  between the positioning pin and the receiving part is from  $91^\circ$  to  $110^\circ$ .
10. (previously presented) The carrier as claimed in Claim 3, wherein the obtuse angle  $\theta$  between the positioning pin and the receiving part is from  $91^\circ$  to  $110^\circ$ .

11. (previously presented) The carrier as claimed in Claim 2, wherein the obtuse angle  $\theta$  between the positioning pin and the receiving part is from  $91^\circ$  to  $96^\circ$ .

.12. (previously presented) The carrier as claimed in Claim 3, wherein the obtuse angle  $\theta$  between the positioning pin and the receiving part is from  $91^\circ$  to  $96^\circ$ .